1	Supporting Information
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3	Contact line dynamics modulated by electrode roughness
4	determines bubble detachment size
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## 13 1. Electrode Preparation

The nickel (Ø500 µm) wire-welded copper leads were fixed onto a pre-14 assembled square frame (Fig. S1). Epoxy resin was prepared by mixing component A 15 and B at a mass ratio of 2:1. Vigorous stirring introduced numerous microbubbles, 16 resulting in an opaque, milky-white mixture. To eliminate entrapped bubbles, the 17 epoxy was centrifuged until achieving optical clarity and high fluidity. After 30 18 minutes of static curing at ambient temperature (28°C), the resin's viscosity increased 19 moderately, at which point it was poured into the frame to encapsulate the electrode. 20 Additional epoxy layers could be applied within 1 hour to ensure complete coverage 21 of both nickel wire and copper leads. The assembly was then cured at room 22 temperature for 12 hours before frame removal. Finally, polished edges were created 23 on the cured epoxy block to facilitate subsequent experimental observations. 24



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Fig. S1. Schematic of the electrode package.

The subsequent Ni electrodes working face was directly polished using sandpaper (wuxi-1200, wuxi-800 and wuxi-400) to prepare three representative Ni electrodes with varying surface roughness, which were utilized as working electrodes. While our embedded electrode design enables precise observation of bubble dynamics, 31 it inherently creates lateral inhomogeneity in electrochemical rates. As noted in recent 32 studies<sup>1,2</sup>, such inhomogeneity may induce density-driven convection. Although this 33 effect does not alter our primary conclusions on contact line dynamics, future work 34 could explicitly quantify its influence through computational fluid dynamics 35 simulations.

## 36 2. Image Analysis

The image analysis program was developed based on the image processing 37 module of MATLAB (R 2022b). Firstly, the background was subtracted, and then the 38 contrast and brightness were adjusted for further binarization. Fig. S2a and S2b 39 present the bubble images after contrast enhancement and binarization processing, 40 respectively. To quantify the contact line dynamics, edge coordinates were extracted 41 from the processed images using computational algorithms, as demonstrated by the 42 scatter plot in Fig. S2c. The bottom radius and contact angle of the bubble were 43 subsequently determined through statistical analysis of the spatial distribution 44 45 characteristics of these edge coordinate points.



47 Fig. S2. (a) the original image with contrast enhancement; (b) the binarized image; (c) Scattered
48 data at the edges; (d) Scatter points used to fit the baseline and tangents.

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To verify the accuracy of our custom-developed algorithm, we compared its 49 contact angle calculations with those obtained from commercial contact angle 50 measurement software (SCA20) at multiple time points. As illustrated in Fig. S3a, 51 representative images from the commercial software's fitting process are displayed 52 (three typical examples shown), while Fig. S3b presents the complete dataset 53 comparison between both methods. The custom algorithm demonstrated consistent 54 reliability throughout the measurement period, with a maximum deviation of less than 55 2° compared to the commercial software. Notably, the automated processing 56 capability of our custom program addressed the critical limitation of the commercial 57 software, which could only perform manual frame-by-frame analysis - a method 58 59 unsuitable for our high-throughput experimental requirements.



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61 Fig. S3. (a) Commercial software SCA20 to measure the contact angle; (b) Comparison of contact
62 angles obtained by the program and results obtained by commercial software.

## 63 3. Contact line dynamics at different current densities

To investigate potential current density effects on hydrogen bubble adhesion 64 dynamics, we first examined bubble growth patterns on the smoothest Ni electrode 65 surface (M1). Fig. S4a presents processed images of the bubble growth process, 66 clearly showing neck formation during expansion. The radius-time curves in Fig. S4b 67 reveal that as the current density increases, the bubble detachment size grows from 68 513 µm to 551 µm, corresponding to an approximately 24% increase in additional 69 buoyancy force. This suggests that the current density generates an additional 70 downward force. As demonstrated by Park et al.<sup>3</sup>, the ion concentration gradient 71 generated near the electrode induces solutal Marangoni flow, which exerts an 72 additional downward force on the bubble (in sulfuric acid electrolyte). The elevated 73 74 current density leads to increased ion concentration gradients, which may explain the slightly larger detachment sizes observed in our experiments. Notably, higher current 75

76 densities accelerated bubble growth rates due to enhanced hydrogen generation, 77 leading to greater molecular hydrogen concentration gradients and interfacial mass 78 transfer fluxes at the electrode surface. Contact line dynamics (Fig. S4c) exhibited 79 universal characteristics regardless of current density: rapid expansion to a maximum 80 radius of 90  $\mu$ m, followed by gradual contraction to 70  $\mu$ m at detachment. Similarly, 81 contact angles (Fig. S4d) demonstrated consistent evolution - rapid increase to 160°, 82 stabilization, then decline to ~150° at detachment.



Fig. S4. (a) Commercial software SCA20 to measure the contact angle; (b) Comparison of contact
angles obtained by the program and results obtained by commercial software.

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Fig. S5 presents the bubble contact line parameters normalized by bubble size to remarkable effects. The size-normalized analysis reveals remarkable

consistency in contact line behavior across different current densities. As shown in 88 Fig. S5a, the contact radius initially increases with bubble growth, reaching a 89 maximum value of 94 µm at a bubble size of 253 µm, after which further bubble 90 expansion leads to contact line contraction. The dynamic contact angle evolution (Fig. 91 S5b) similarly demonstrates current-density-independent characteristics, beginning to 92 decrease when the bubble reaches 377 µm in size. These findings conclusively 93 demonstrate that the contact line evolution on a given electrode surface is governed 94 by surface topography and the resultant force balance, rather than being influenced by 95 current density variations. 96



98 Fig. S5. Under different current densities: (a) Relationship between contact radius and bubble size;
99 (b) Relationship between dynamic contact Angle and bubble size.

Fig S6 presents the Ni electrode surface morphology before and after HER using quasi-in situ AFM measurements during 10 min of electrolysis at 20 mA/cm<sup>2</sup>, revealing only marginal roughness increases (M1:  $5.64\rightarrow 5.69$  nm; M2:  $8.73\rightarrow 8.97$ nm; M3:  $13.88\rightarrow 14.32$  nm) that confirm negligible structural modifications, while the bubble behavior appears dominated by initial surface roughness rather than these 105 minimal HER-induced changes due to the orders-of-magnitude larger bubble106 dimensions compared to roughness variations.



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108 Fig. S6. Two-dimensional morphology of nickel electrode before HER: (a) M1, (b) M2, (c) M3;

109 Two-dimensional morphology of nickel electrode after HER: (d) M1, (e) M2, (f) M3.

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